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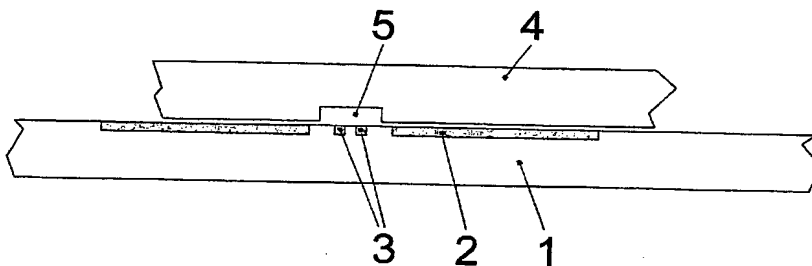
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(54) Title: METHOD OF FORMING A SEMICONDUCTOR DEVICE



(57) Abstract: A method of forming a semiconductor device from a semiconductor substrate (1) comprising circuitry (2) and terminal means (3) for establishing electrical connection to the circuitry; and a sheet (4) for forming a further layer of the device, the sheet comprising at least one groove (5). Adhesive is applied to at least one of the substrate (1) and the sheet (4); the substrate and the sheet are then aligned in a position such that the groove (5) faces the terminal means (3); and the substrate and the sheet are then attached together by means of the adhesive.